

Description

The HN6373 uses advanced trench technology

to provide excellent $R_{\text{DS}(\text{ON})},$ low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = -30V I_D =-50 A

 $R_{DS(ON)} < 13m\Omega @ V_{GS} = -10V$

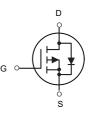
Application

Battery protection

Load switch Uninterruptible power supply







P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HN6373	DFN3X3-8L	HN6373 XXYYS	5000

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

		Rating		Units
Symbol	Parameter	10s	Steady State	Units
VDS	Drain-Source Voltage	-	-30	
VGS	Gate-Source Voltage	±	20	V
I₀@Tc=25℃	Continuous Drain Current, V _{GS} @ -10V ¹		-50	
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ -10V ¹	-/	-27	
I₀@T₄=25℃	Continuous Drain Current, VGS @ -10V1	-14.3	-9	А
ID@TA=70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-11.4	-7.2	А
IDM	Pulsed Drain Current ²	-130		А
EAS	Single Pulse Avalanche Energy ³	125		mJ
IAS	Avalanche Current	-50		А
P _D @T _C =25℃	Total Power Dissipation ⁴	37		W
P _D @T _A =25°C	Total Power Dissipation ⁴	4.2	1.67	W
TSTG	Storage Temperature Range	-55 t	-55 to 150	
TJ	Operating Junction Temperature Range	-55 to 150		°C



P-Channe	el Enhancement	Mode MOSFET

R₀JA	Thermal Resistance Junction-Ambient ¹	75	°C/W
R₀JA	Thermal Resistance Junction-Ambient ¹ (t ≤10s)	30	°C/W
R _θ JC	Thermal Resistance Junction-Case ¹	3.36	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
∆BVbss/∆Tj	BVDSS Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.0232		V/°C
	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-30A		9	13	
RDS(ON)		V _{GS} =-4.5V , I _D =-15A		16	22	mΩ
VGS(th)	Gate Threshold Voltage		-1.2		-2.5	V
$\bigtriangleup V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =-250uA		4.6		mV/°C
		V _{DS} =-24V , V _{GS} =0V , T _J =25°C			-1	
ldss	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =55°C			-5	uA
lgss	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-30A		30		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		9		Ω
Qg	Total Gate Charge (-4.5V)	V _{DS} =-15V , V _{GS} =-4.5V , I _D =- 15A		22		
Qgs	Gate-Source Charge			8.7		nC
Qgd	Gate-Drain Charge			7.2		
Td(on)	Turn-On Delay Time			8		- ns
Tr	Rise Time	V _{DD} =-15V , V _{GS} =-10V ,		73.7		
Td(off)	Turn-Off Delay Time	—R _G =3.3 —I _D =-15A		61.8		
Tf	Fall Time	ID ISA		24.4		
Ciss	Input Capacitance			2215		
Coss	Output Capacitance			310		pF
Crss	Reverse Transfer Capacitance			237		
ls	Continuous Source Current ^{1,5}				-42	Α
lsм	Pulsed Source Current ^{2,5}	$-V_{G}=V_{D}=0V$, Force Current			-130	Α
Vsd	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1	V
trr	Reverse Recovery Time	IF=-15A , dl/dt=100A/µs ,		19		nS
Qrr	Reverse Recovery Charge	TJ=25°C		9		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leq 300us duty cycle \leq 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V V_{GS} =-10V,L=0.1mH,I_{AS}=-50A,

4.The power dissipation is limited by 150°C junction temperature

5.The data is theoretically the same as $I_{\text{\tiny D}}$ and $I_{\text{\tiny DM}}$, in real applications , should be limited by total power dissipation.



Typical Characteristics

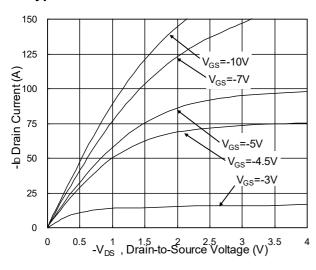


Fig.1 Typical Output Characteristics

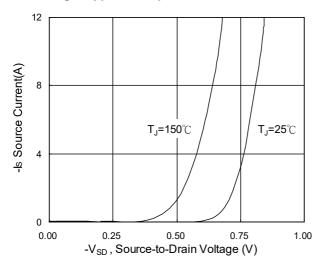
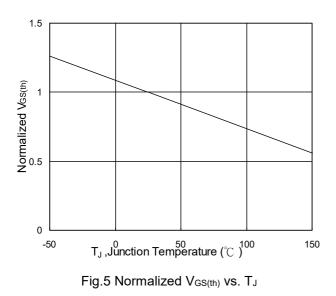


Fig.3 Forward Characteristics of Reverse



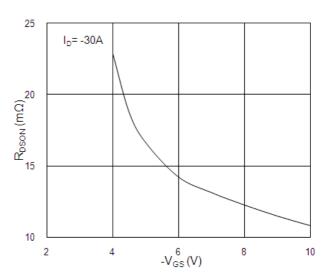


Fig.2 On-Resistance vs. G-S Voltage

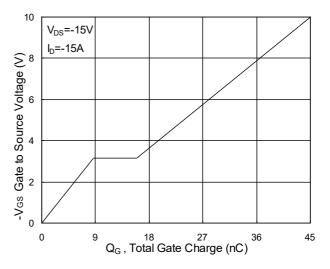


Fig.4 Gate-Charge Characteristics

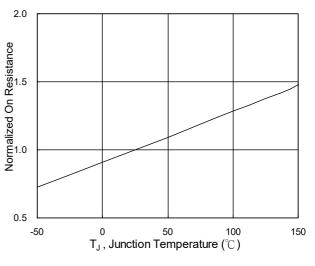


Fig.6 Normalized R_{DSON} vs. T_J



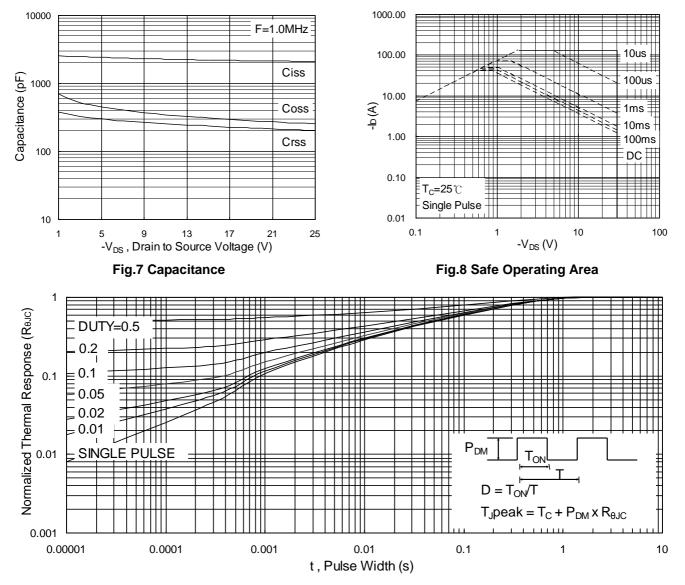


Fig.9 Normalized Maximum Transient Thermal Impedance

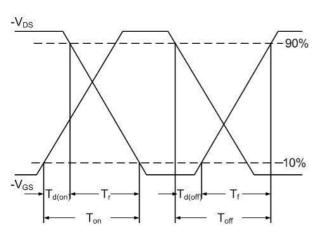


Fig.10 Switching Time Waveform

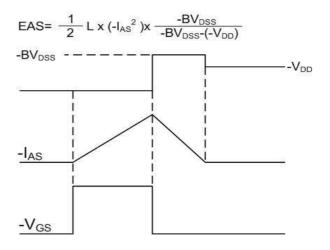
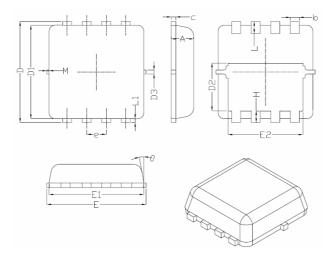


Fig.11 Unclamped Inductive Switching Waveform



DFN3X3-8L Package Information



Symphol	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
e	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
М	*	*	0.15	
θ		10 [°]	12 [°]	



Attention

Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.

• HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.

• Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

• HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could

give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

• In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

• No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.

Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production.
HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.